







General Information	
Series	KONNEKT Auto COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra- Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	201.24 mg
Chip Size	1210-2
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
Т	5.1mm +/-0.4mm
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

Specifications	
Capacitance	1,400 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2,400 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 PPM/C
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 04/30/2025 © 2006 - 2025 YAGEO